

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments
6	BRS	L6	58210	(flat\$8 or planar\$4 or polish\$4 or CMP) same (bump or stud or ball)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:04	
7	BRS	L7	3940	6 same (reflow\$4 or re-flow\$4 or solder\$4)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:07	
8	BRS	L8	1072	7 and (wirebond\$4 or (wir\$4 adj bond\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:08	
9	BRS	L9	981	8 and (UBM or (under adj (bump or ball) or metal\$8))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM-TDB	2003/08/26 16:09	